General Description

The AGM305A combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
30V	4.5mΩ	80A

PDFN5*6 Pin Configuration

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM305A	AGM305A	PDFN5*6	330mm	12mm	3000

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	30	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25℃) **(Note 1)**	80	A
	Drain Current-Continuous(Tc=100℃)	60	A
IDM (pluse)	Drain Current-Continuous@ Current-Pulsed **(Note 2)**	320	A
PD	Maximum Power Dissipation(Tc=25℃)	70	w
	Maximum Power Dissipation(Tc=100℃)	28	w
EAS	Avalanche energy **(Note 3)**	172	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	℃

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State)[1]	---	20	℃/W
RθJC	Thermal Resistance Junction-Case[1]	---	1.8	℃/W

Table 3. Electrical Characteristics (TJ=25℃unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	30	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=30V,VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	1.0	1.5	2.5	V
gFS	Forward Transconductance	VDS=5V,ID=10A	--	13	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=20A	--	4.5	5.4	mΩ
		VGS=4.5V, ID=15A	--	5.8	8.2	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=15V,VGS=0V, F=1MHZ	--	1240	--	pF
Coss	Output Capacitance		--	235	--	pF
Crss	Reverse Transfer Capacitance		--	185	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz	--	3.7	--	Ω
Switching Times						
td(on)	Turn-on Delay Time	VGS=10V,VDS=10V, ID=30A,RGEN=2.7Ω, RL=1Ω	--	18	--	nS
tr	Turn-on Rise Time		--	14	--	nS
td(off)	Turn-Off Delay Time		--	55	--	nS
tf	Turn-Off Fall Time		--	8	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=10V, ID=30A	--	27	--	nC
Qgs	Gate-Source Charge		--	6.3	--	nC
Qgd	Gate-Drain Charge		--	3.6	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)		--	--	80	A
VSD	Forward on Voltage	VGS=0V,IS=20A	--	--	1.2	V
trr	Reverse Recovery Time	IF=20A , dI/dt=100A/μs , TJ=25℃	--	--	--	ns
Qrr	Reverse Recovery Charge		--	--	--	nc

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25℃

Figure A: Gate Charge Test Circuit and Waveform

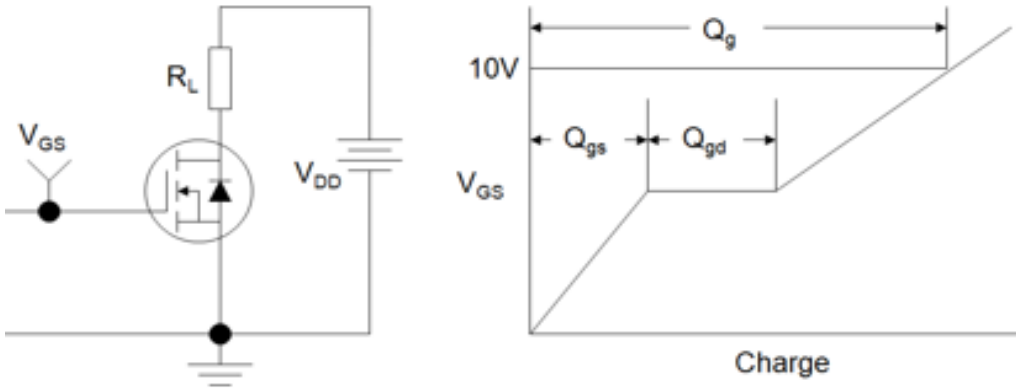


Figure B: Resistive Switching Test Circuit and Waveform

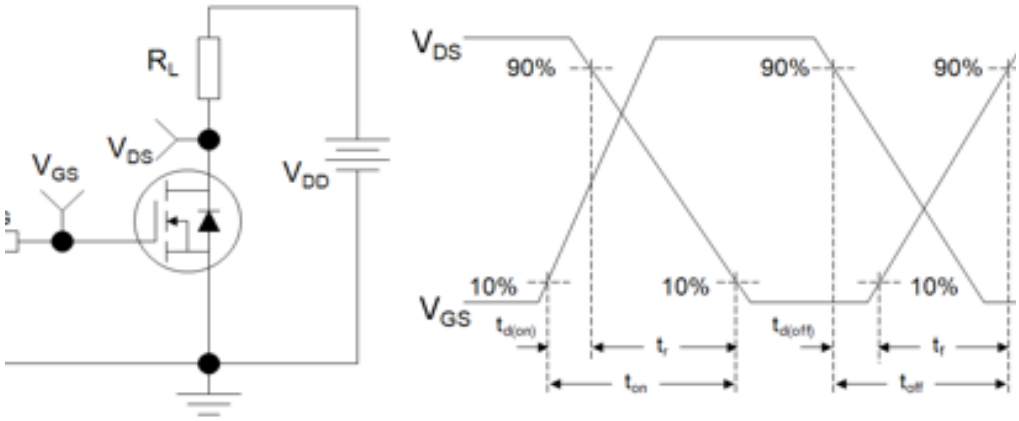
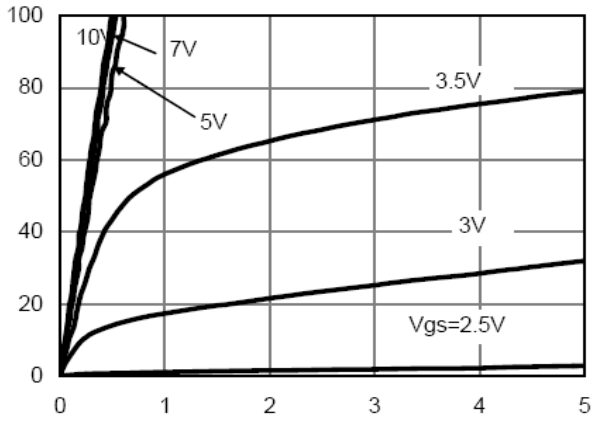


Figure C: Unclamped Inductive Switching Test Circuit and Waveform

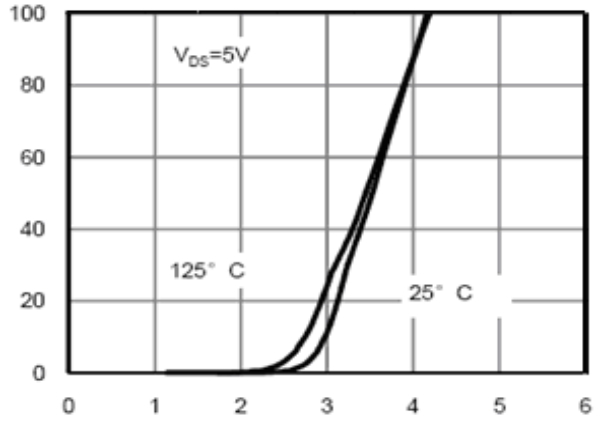
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure 1. Output Characteristics



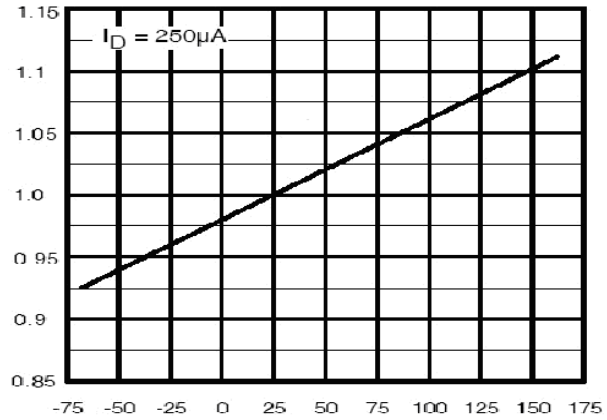
VDS Drain-to-Source Voltage(V)

Figure 2. Transfer Characteristics



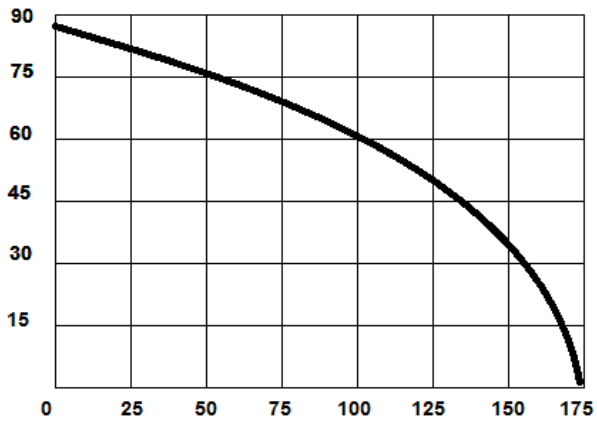
VGS Gate-to-Source Voltage(V)

Figure 3. Max BV_{DSS} vs Junction Temperature



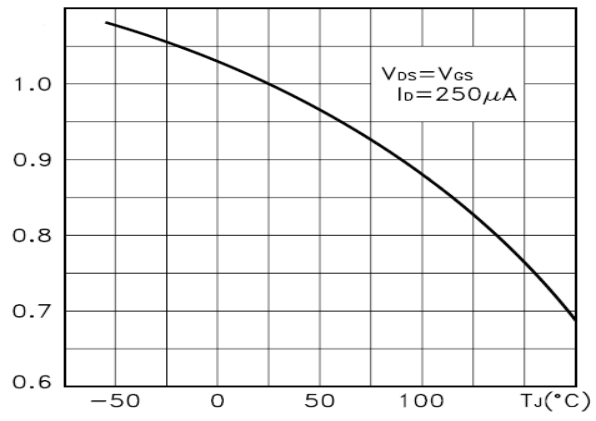
T_J-Junction Temperature(℃)

Figure 4. Drain Current



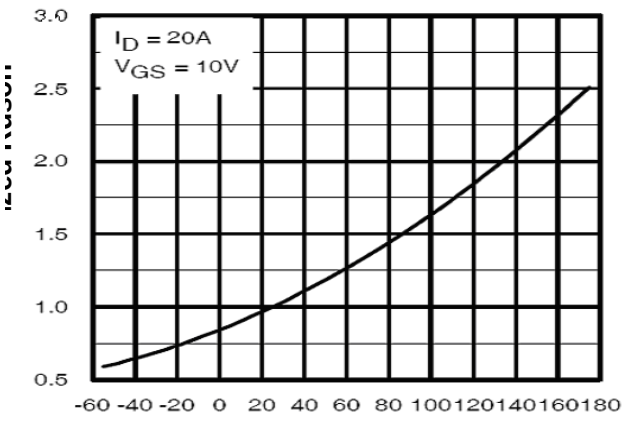
T_J-Junction Temperature(℃)

Figure 5. $V_{GS(th)}$ vs Junction Temperature



T_J-Junction Temperature(℃)

Figure 6. $R_{DS(ON)}$ vs Junction Temperature



T_J-Junction Temperature(℃)

Figure 7. Gate Charge Waveforms

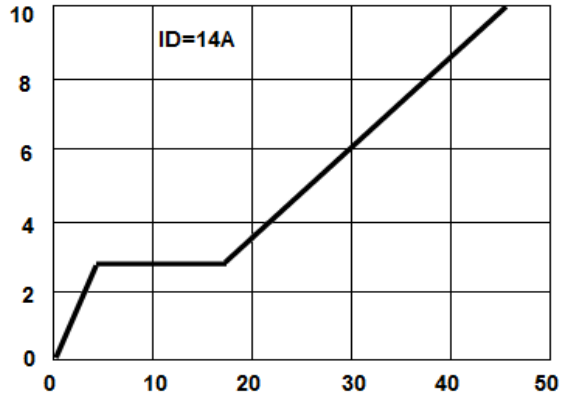


Figure 8. Capacitance

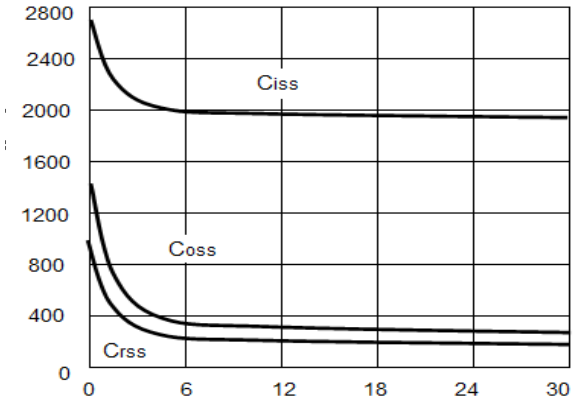


Figure 9. Body-Diode Characteristics

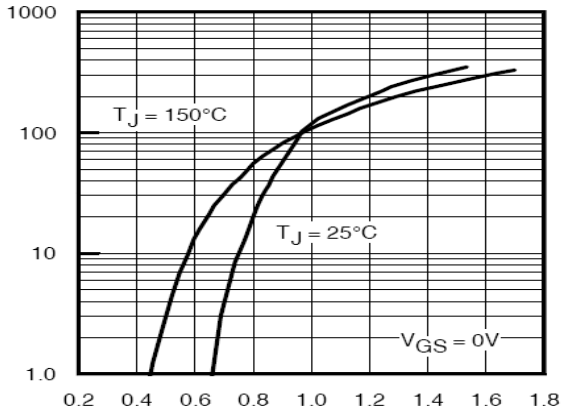


Figure 10. Maximum Safe Operating Area

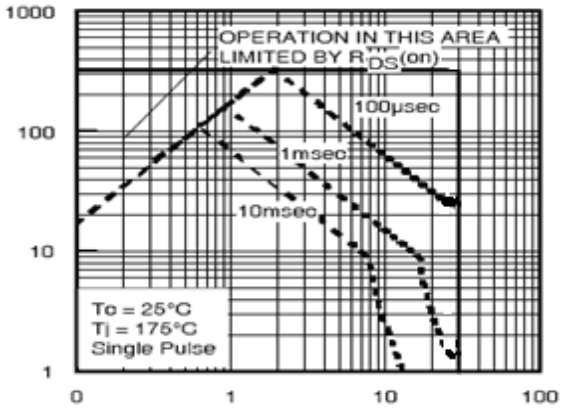
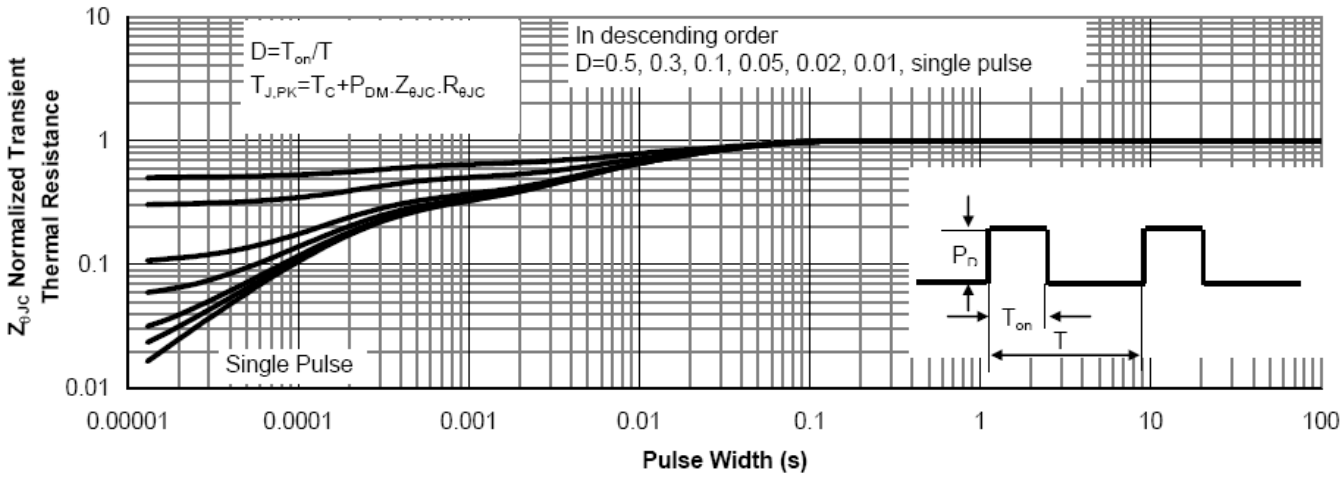
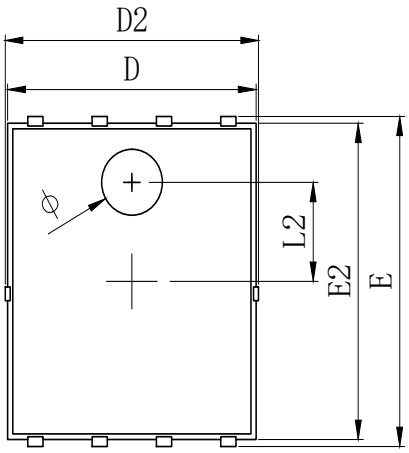
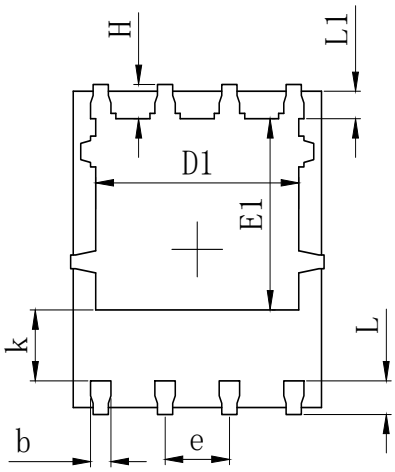


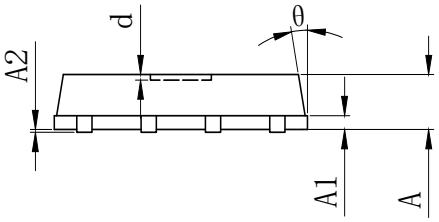
Figure 11. Normalized Maximum Transient Thermal Impedance



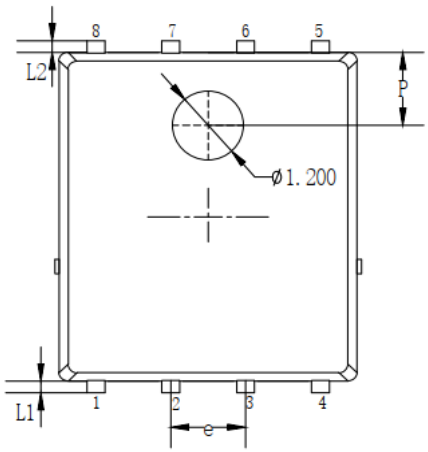
●Dimensions（PDFN5*6）

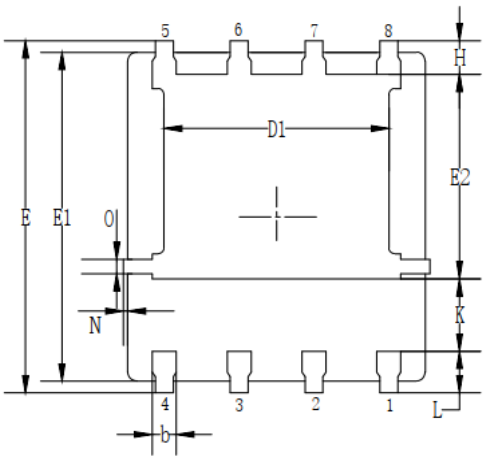


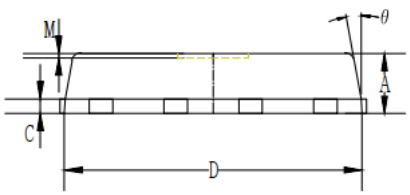




SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.900	1.000	1.100
A1	0.254 REF.		
A2	0~0.05		
D	4.824	4.900	4.976
D1	3.910	4.010	4.110
D2	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e	1.270 TYP.		
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
L2	1.800 REF.		
k	1.190	1.290	1.390
H	0.549	0.625	0.701
θ	8°	10°	12°
ϕ	1.100	1.200	1.300
d			0.100







Symbols	Millimeters		
	MIN.	NOM.	MAX.
A	0.90	1.05	1.20
b	0.35	0.40	0.50
C	0.20	0.25	0.35
D	4.90	5.05	5.20
D1	3.72	3.82	3.92
E	6.00	6.15	6.30
E1	5.60	5.75	5.90
E2	3.47	3.57	3.67
e	1.27 BSC.		
H	0.48	0.58	0.68
K	1.17	1.27	1.37
L	0.64	0.74	0.84
L1/L2	0.20 REF.		
θ	8°	10°	12°
M	0.08 REF.		
N	0	-	0.15
O	0.25 REF.		
P	1.28 REF.		

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